

# WEST Search History for Application 10580946

Creation Date: 2008122210:20

Query	DB	Op.	Plur.	Thes.	Date
(374/179,180)![CCLS]	PGPB, USPT, USOC, EPAB, JPAB	ADJ			12-19-2008
((374/179,180)![CCLS] ) and (substrate or wafer or semiconductor or substrate near support or substrate near holder)	PGPB, USPT, USOC, EPAB, JPAB	ADJ	YES		12-19-2008
((374/179,180)![CCLS] ) and (substrate or wafer or semiconductor or substrate near support\$3 or substrate near holder)	PGPB, USPT, USOC, EPAB, JPAB	ADJ	YES		12-19-2008
((374/179,180)![CCLS] ) and (substrate or wafer or semiconductor or substrate near support\$3 or substrate near holder or susceptor or effector or robotic arm)	PGPB, USPT, USOC, EPAB, JPAB	ADJ	YES		12-19-2008
((374/179,180)![CCLS] ) and (substrate or wafer or semiconductor or substrate near support\$3 or substrate near holder or susceptor or effector or robotic arm) and (thermocouple or thermoelectric couple)	PGPB, USPT, USOC, EPAB, JPAB	ADJ	YES		12-19-2008
((374/179,180)![CCLS] ) and (thermocouple)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
((374/179,180)![CCLS] and (thermocouple) ) and (crush\$3)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008

374/.ccls. and (crush\$4) and (thermocouple)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
374/.ccls. and (crush\$4) same (thermocouple)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
374/.ccls. and (compact\$4) same (thermocouple)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
374/.ccls. and (compacted or compacting or compactable) same (thermocouple)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
374/.ccls.	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
(374/.ccls. ) and (compact\$4 near metal or crush\$4 near metal)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
(374/.ccls. ) and (compact\$4 near copper or crush\$4 near copper)	PGPB, USPT, USOC, EPAB,	ADJ	YES		12-19-2008

	JPAB, DWPI, TDBD			
(374/.ccls. ) and (compact\$4 near gold or crush\$4 near gold)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(374/.ccls. ) and (compact\$4 near aluminum or crush\$4 near aluminum)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(374/.ccls. ) and (compact\$4 near platina or crush\$4 near platina)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(374/.ccls. ) and (compact\$4 near platinum or crush\$4 near platinum)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(374/.ccls. ) and (compact\$4 near iron or crush\$4 near iron)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(374/.ccls. ) and (compact\$4 near15 metal or crush\$4 near15 metal)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
		ADJ	YES	12-19-2008

(374/.ccls. and (compact\$4 near15 metal or crush\$4 near15 metal) ) and (thermocouple)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD				
(374/.ccls. and (compact\$4 near15 metal or crush\$4 near15 metal) ) and (thermocouple) and (reflect\$3 near radiat\$4 or reflect\$3 near infrared or reflect\$3 near rays or reflect\$3 near waves)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
(374/.ccls. and (compact\$4 near15 metal or crush\$4 near15 metal) ) and (reflect\$3 near radiat\$4 or reflect\$3 near infrared or reflect\$3 near rays or reflect\$3 near waves)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
(374/.ccls. ) and (sheath) and (thermocouple) and (reflect\$3 near radiat\$4 or reflect\$3 near infrared or reflect\$3 near rays or reflect\$3 near waves)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
(374/.ccls. ) and (thermocouple) same (reflect\$3 near radiat\$4 or reflect\$3 near infrared or reflect\$3 near rays or reflect\$3 near waves or reflect\$3 near heat)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
(374/.ccls. ) and (thermocouple) same (reflect\$3 near coat\$3)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES		12-19-2008
(thermocouple) same (reflect\$3 near coat\$3) same (substrate or wafer)	PGPB, USPT, USOC, EPAB,	ADJ	YES		12-19-2008

	JPAB, DWPI, TDBD			
(thermocouple) same (reflect\$3 near film or reflect\$3 near sheath or reflect\$3 near material) same (substrate or wafer)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(thermocouple) same (reflect\$3 near film or reflect\$3 near sheath or reflect\$3 near material)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
((thermocouple) same (reflect\$3 near film or reflect\$3 near sheath or reflect\$3 near material) ) and (compacted or compacting or compactable or crushed or crushing or crushable) same	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
((thermocouple) same (reflect\$3 near film or reflect\$3 near sheath or reflect\$3 near material) ) and (compacted or compacting or compactable or crushed or crushable or crushing)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(compacted or compacting or compactable or crushed or crushable or crushing) same (thermocouple) same (reflect\$4)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(compacted or compacting or compactable or crushed or crushable or crushing) same (thermocouple) same (reflect\$4 near casing or reflect\$3 near housing or reflect\$3 near sleeve or reflect\$3 near jacket or reflect\$3 near shield or reflect\$3 near sheath or reflect\$3 near coat\$3 or reflect\$3 near paint or reflect\$3 near film)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
136/.ccls.		ADJ	YES	12-19-2008

	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD			
(136/\$.ccls. ) and (thermocouple)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(compacted or compacting or compactable or crushed or crushable or crushing) same (thermocouple) and (136/\$.ccls. and (thermocouple) )	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
((compacted or compacting or compactable or crushed or crushable or crushing) same (thermocouple) and 136/\$.ccls. and (thermocouple) ) and (substrate or wafer)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(compacted or compacting or compactable or crushed or crushable or crushing) same (thermocouple) and (reflect\$3) and (136/\$.ccls. and (thermocouple) )	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(374/\$.ccls. ) and (thermocouple) same (reflect\$3)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(374/\$.ccls. and (thermocouple) same (reflect\$3) ) and (substrate or wafer)	PGPB, USPT, USOC, EPAB,	ADJ	YES	12-19-2008

	JPAB, DWPI, TDBD			
136/200	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(136/200 ) and (thermocouple)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
374/121 and (thermocouple)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
374/135 and (thermocouple)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
(374/135 and (thermocouple) ) and (substrate or wafer)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
374/121 and (thermocouple) and (substrate or wafer)	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD	ADJ	YES	12-19-2008
374/121 and (thermocouple) same (substrate or wafer)		ADJ	YES	12-19-2008

	PGPB, USPT, USOC, EPAB, JPAB, DWPI, TDBD			
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